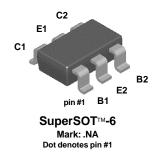


# **FMB100**



# **NPN Multi-Chip General Purpose Amplifier**

This device is designed for general purpose amplifier applications at collector currents to 300 mA. Sourced from Process 10.

#### **Absolute Maximum Ratings\*** T<sub>A</sub> =25°C unless otherwise noted

Symbol	Parameter	Value	Units	
$V_{CEO}$	Collector-Emitter Voltage	45	V	
V <sub>CBO</sub>	Collector-Base Voltage	75	V	
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V	
Ic	Collector Current - Continuous	500	mA	
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C	

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# 

Symbol	Characteristic	Max	Units	
		FMB100		
P <sub>D</sub>	Total Device Dissipation	700	mW	
	Derate above 25°C	5.6	mW/°C	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	180	°C/W	

# **NPN Multi-Chip General Purpose Amplifier**

(continued)

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T<sub>A</sub>= 25°C unless otherwise noted

	Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
	OFF CHAI	OFF CHARACTERISTICS					
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10  \mu A,  I_B = 0$	75			V
$ \begin{array}{ c c c c c c c c } \hline L_{CBO} & Collector Cutoff Current & V_{CB} = 60 \ V & 50 & nA \\ \hline L_{CES} & Collector Cutoff Current & V_{CE} = 40 \ V & 50 & nA \\ \hline L_{EBO} & Emitter Cutoff Current & V_{EB} = 4 \ V & 50 & nA \\ \hline \\ \hline ON CHARACTERISTICS & & & & & & & & & & & & & & & & & & &$	BV <sub>CEO</sub>		$I_C = 1 \text{ mA}, I_E = 0$	45			V
$\begin{array}{ c c c c c c }\hline I_{CES} & Collector Cutoff Current & V_{CE} = 40 \ V & 50 \ nA \\ \hline I_{EBO} & Emitter Cutoff Current & V_{EB} = 4 \ V & 50 \ nA \\ \hline \\ \hline ON CHARACTERISTICS \\ \hline h_{FE} & DC Current Gain & I_{C} = 100 \ \mu\text{A}, \ V_{CE} = 1.0 \ V & 100 \ I_{C} = 100 \ m\text{A}, \ V_{CE} = 1.0 \ V & 100 \ I_{C} = 100 \ m\text{A}, \ V_{CE} = 1.0 \ V^* & 100 \ I_{C} = 150 \ m\text{A}, \ V_{CE} = 5.0 \ V^* & 100 \ I_{C} = 150 \ m\text{A}, \ V_{CE} = 5.0 \ V^* & 100 \ I_{C} = 200 \ m\text{A}, \ I_{B} = 20 \ m\text{A}^* & 0.2 \ V \\ \hline V_{BE(sat)} & Base-Emitter Saturation Voltage & I_{C} = 10 \ m\text{A}, \ I_{B} = 1.0 \ m\text{A} & 0.85 \ V \ I_{C} = 200 \ m\text{A}, \ I_{B} = 20 \ m\text{A}^* & 1.0 \ V \\ \hline \\ SMALL SIGNAL CHARACTERISTICS \\ \hline f_{T} & Current Gain - Bandwidth Product & V_{CE} = 20 \ V, \ I_{C} = 20 \ m\text{A} & 300 \ MHz \\ \hline \end{array}$	BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10  \mu A,  I_C = 0$	6.0			V
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	I <sub>CBO</sub>	Collector Cutoff Current	V <sub>CB</sub> = 60 V			50	nA
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>CES</sub>	Collector Cutoff Current	V <sub>CE</sub> = 40 V			50	nA
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	I <sub>EBO</sub>	Emitter Cutoff Current	V <sub>EB</sub> = 4 V			50	nA
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	h <sub>FE</sub>	DC Current Gain	$I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	100 100			
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			, 02	100		350	
$I_{C} = 200 \text{ mA}, I_{B} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{B} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$ $I_{C} = 200 \text{ mA}, I_{D} = 20 \text{ mA}^{*}$	V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage					
$f_T$ Current Gain - Bandwidth Product $V_{CE} = 20 \text{ V}, I_C = 20 \text{ mA}$ 300 MHz	V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	, -				•
Coho Output Capacitance V <sub>CB</sub> = 5.0 V, f = 1.0 MHz 3.5 pF	SMALL SI		V <sub>CE</sub> = 20 V, I <sub>C</sub> = 20 mA		300		MHz
	C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 5.0 V, f = 1.0 MHz		3.5		pF

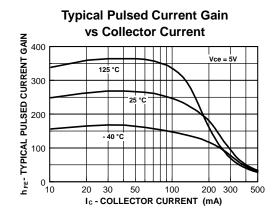
 $I_C = 100 \mu A$ ,  $V_{CE} = 5.0 V$ ,

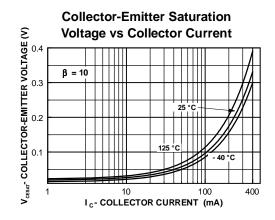
 $R_G = 2.0 \text{ k}\Omega$ , f = 1.0 kHz

Noise Figure

NF

# **Typical Characteristics**





2.5

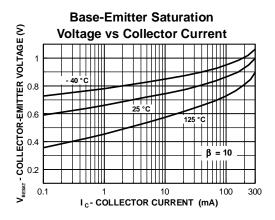
dB

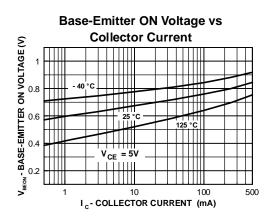
<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

### NPN Multi-Chip General Purpose Amplifier

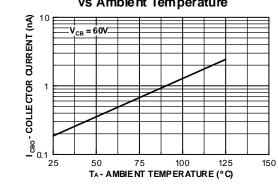
(continued)

### Typical Characteristics (continued)

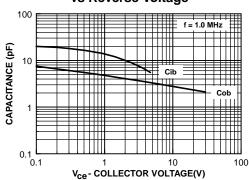




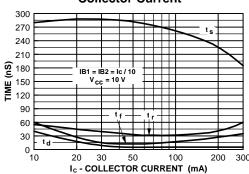
# Collector-Cutoff Current vs Ambient Temperature



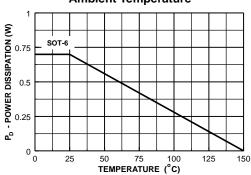
# Input and Output Capacitance vs Reverse Voltage



Switching Times vs Collector Current



Power Dissipation vs Ambient Temperature



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